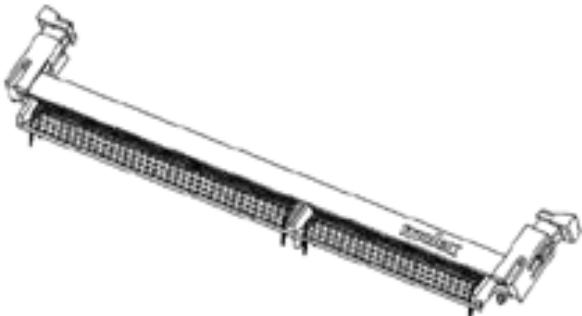


Part Number : 783730001

Product Description : 1.00mm Pitch DDR3
DIMM Socket, 25° Angle, Through Hole, with
Beveled Metal Pins, Black Housing and
Latches, 0.76µm Gold (Au) Plating, 2.79mm
Solder Tail Length, 1.57mm PCB Thickness,
1.5V Center Voltage Key, 240 Circuits



Series Number : 78373

Status : Planned for Obsolescence

Product Category : Memory Module
Connectors

Documents & Resources

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	
EU ELV	Not Relevant
Low-Halogen Status	Not Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per D(2023)3788-DC (14 Jun 2023)
EU RoHS	Compliant per EU 2015/863

Multiple Part Product Compliance Statements

- Eu RoHS
- REACH SVHC
- Low-Halogen

Multiple Part Industry Compliance Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

EU RoHS Certificate of Compliance

Part Details

General

Status	Planned for Obsolescence
Category	Memory Module Connectors
Series	78373
Description	1.00mm Pitch DDR3 DIMM Socket, 25° Angle, Through Hole, with Beveled Metal Pins, Black Housing and Latches, 0.76µm Gold (Au) Plating, 2.79mm Solder Tail Length, 1.57mm PCB Thickness, 1.5V Center Voltage Key, 240 Circuits
Component Type	Socket
JEDEC Outline	MO-269
Product Family	DDR3 DIMM Sockets
Product Name	DDR3 DIMM
UPC	883906206697

Agency

CSA	LR19980
UL	E29179

Electrical

Current - Maximum per Contact	1.0A
Voltage Key	Center
Voltage - Maximum	30V AC (RMS)/DC

Physical

Circuits (Loaded)	240
Circuits (maximum)	240
Durability (mating cycles max)	25
Entry Angle	25° Angle
Flammability	94V-0
Housing Color	Black
Keying to Mating Part	Yes
Latch Color	Black

Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	11.547/g
Packaging Type	Tray
PC Tail Length	2.79mm
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness - Recommended	1.57mm
Pitch - Mating Interface	1.00mm
Pitch - Termination Interface	1.00mm
Plating min - Mating	0.762 μ m
Plating min - Termination	2.540 μ m
Temperature Range - Operating	-55° to +85°C
Termination Interface Style	Through Hole

Solder Process Data

Max-Duration	10
Lead-Free Process Capability	SMC&WAVE
Max-Cycle	2
Max-Temp	260

This document was generated on Jan 24, 2024